

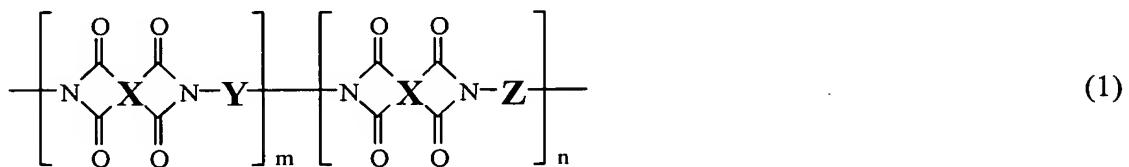
AMENDMENTS TO THE CLAIMS

Claim 1 (Currently Amended): A The wafer dicing/die bonding sheet according to
Claim 2, wherein comprising a backing member, an adhesive layer formed thereon, and a
protective member for protecting the adhesive layer,

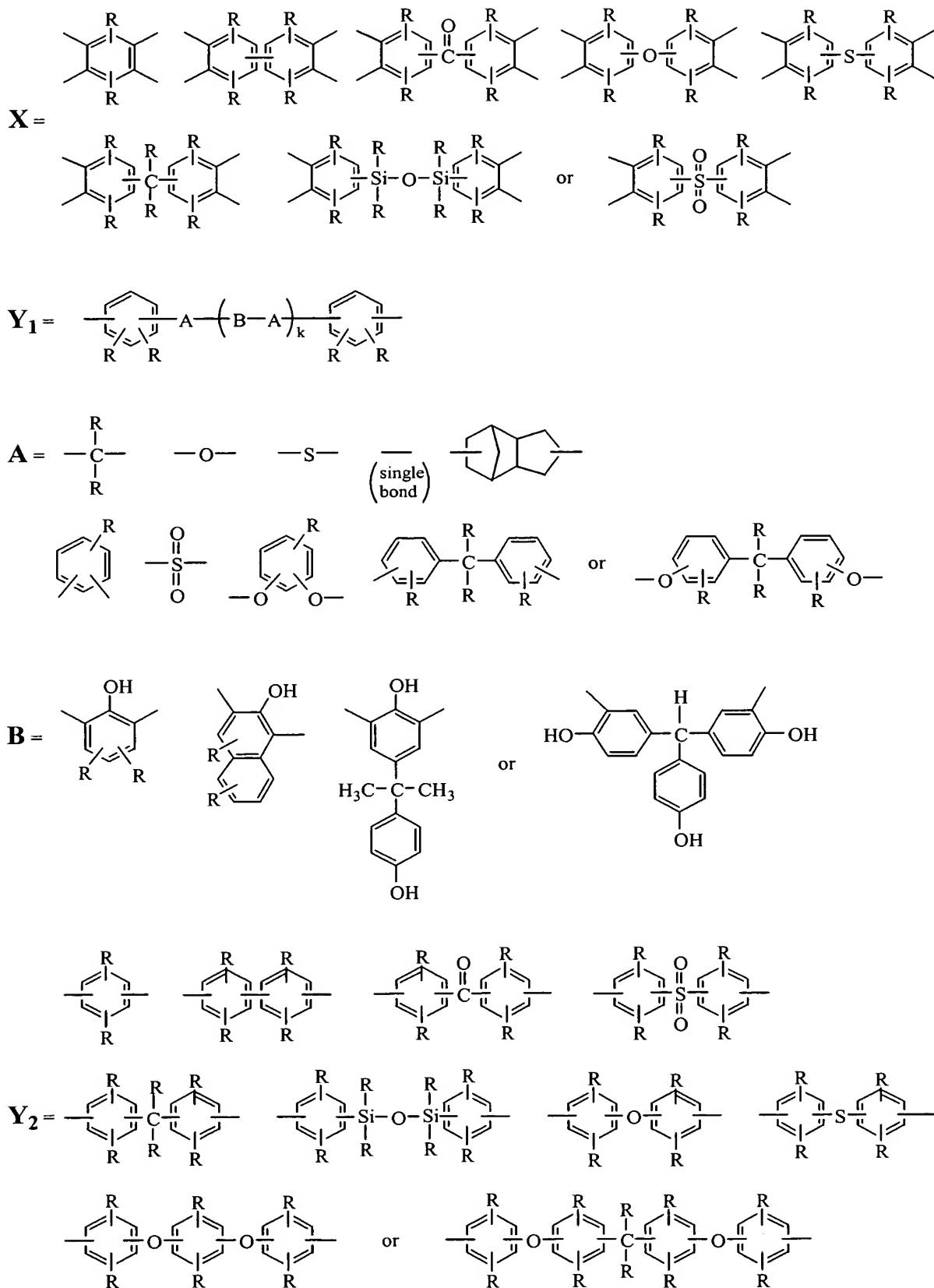
said adhesive layer being made of an adhesive composition comprising a phenolic
hydroxyl radical bearing polyimide resin, an epoxy resin, and an epoxy resin curing agent,
the ratio of the total weight of the epoxy resin and the epoxy resin curing agent to the weight
of the polyimide resin being from 0.1:1 to 3:1.

Claim 2 (Currently Amended): The A wafer dicing/die bonding sheet of claim 1
comprising a backing member, an adhesive layer on the backing member, and a protective
member on the adhesive layer, said adhesive layer being made of an adhesive composition,
wherein

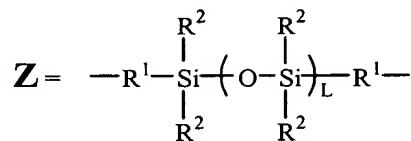
said adhesive composition is a heat resistant polyimide resin composition comprising
a polyimide resin having phenolic hydroxyl radicals in or at the ends of the polyimide
skeleton, comprising recurring units of the structural formula (1) or (2) shown below and
prepared using a diamine or monoamine bearing an aromatic ring having an amino radical
and another aromatic ring having a phenolic hydroxyl radical, an epoxy resin having at least
two glycidyl radicals, and an epoxy resin curing agent,
the structural formula (1) or (2) being:



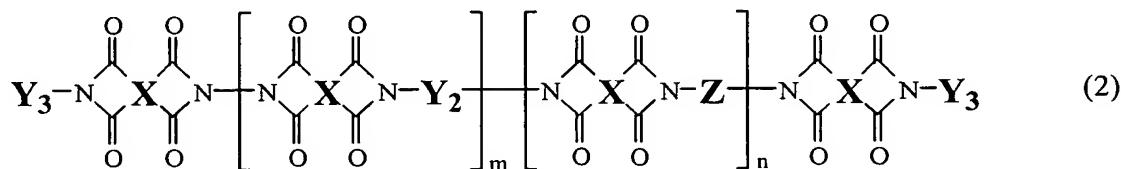
wherein X is at least one tetravalent organic radical as shown below, Y is a divalent organic radical comprising at least one diamine residue (Y₁) having a phenolic hydroxyl radical as shown below and at least one aromatic diamine residue (Y₂) as shown below, the molar ratio of Y₁/(Y₁+Y₂) being from 0.01 to 1, Z is at least one siloxane diamine residue as shown below, m and n are natural numbers satisfying $0.1 \leq m/(m+n) \leq 0.99$ and $10 \leq m+n \leq 500$,



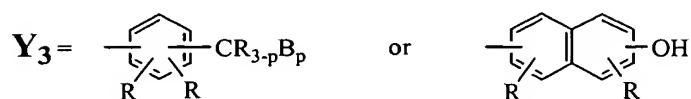
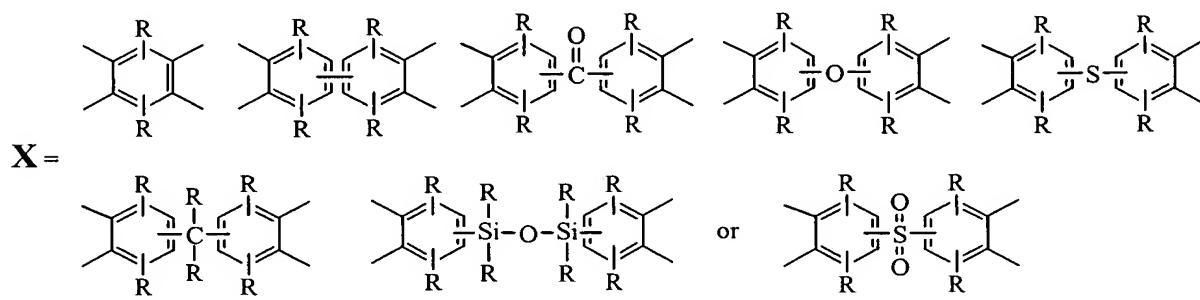
wherein k is a natural number of 1 to 5, R is each independently a hydrogen atom, a halogen atom or a substituted or unsubstituted monovalent hydrocarbon radical having 1 to 8 carbon atoms,

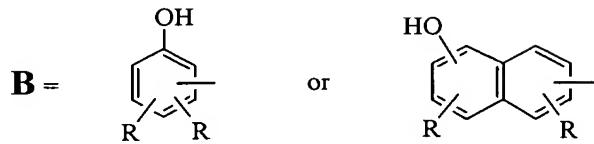


wherein R¹ is each independently an alkylene radical of 1 to 8 carbon atoms or arylene radical, R² is each independently an alkyl or alkoxy radical of 1 to 8 carbon atoms which may be branched, or aryl radical, and L is an integer of 4 to 60,

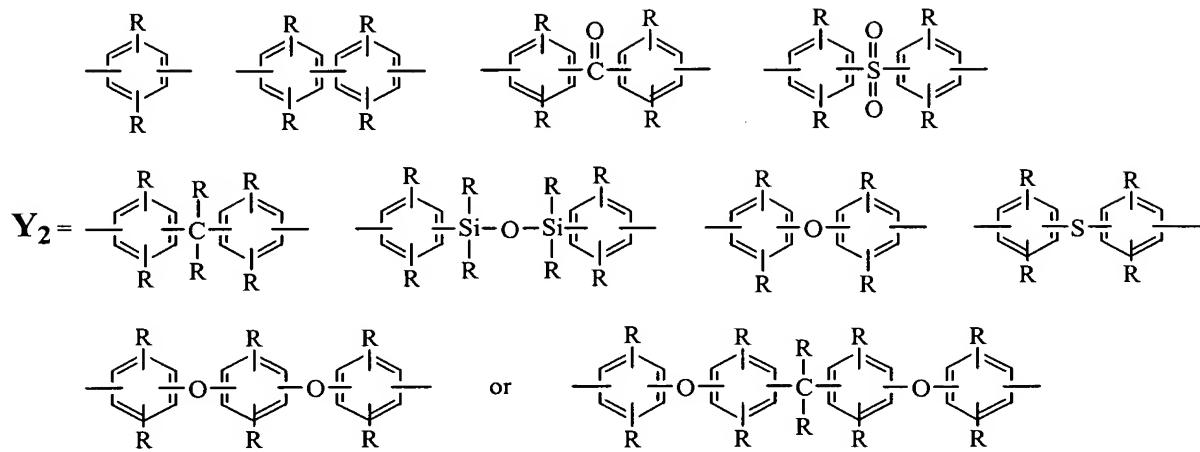


wherein X is at least one tetravalent organic radical as shown below, Y₂ is a divalent organic radical comprising at least one aromatic diamine residue as shown below, Y₃ is a monovalent organic radical comprising at least one aromatic amine residue having a phenolic hydroxyl radical as shown below, Z is at least one siloxane diamine residue as shown below, m and n are natural numbers satisfying 0.1 ≤ m/(m+n) ≤ 0.99 and 10 ≤ m+n ≤ 500,

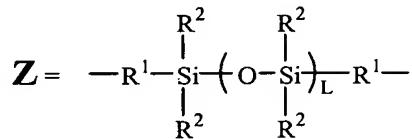




wherein p in Y_3 is a natural number of 1 to 3,



wherein R is each independently a hydrogen atom, a halogen atom or a substituted or unsubstituted monovalent hydrocarbon radical having 1 to 8 carbon atoms,



wherein R^1 is each independently an alkylene radical of 1 to 8 carbon atoms or arylene radical, R^2 is each independently an alkyl or alkoxy radical of 1 to 8 carbon atoms which may be branched or aryl radical, and L is an integer of 4 to 60.

Claim 3 (Currently Amended): The wafer dicing/die bonding sheet of claim 1 according to Claim 2, wherein said adhesive composition further comprises a silane coupling agent.

Claim 4 (New): The wafer dicing/die bonding sheet according to Claim 3, wherein said adhesive composition comprises 0.1 to 5 parts by weight of the silane coupling agent per 100 parts by weight of the polyimide resin and the epoxy resin curing agent combined.

Claim 5 (New): The wafer dicing/die bonding sheet according to Claim 2, wherein said adhesive composition further comprises a curing catalyst selected from the group consisting of phosphorus catalysts and amine catalysts.

Claim 6 (New): The wafer dicing/die bonding sheet according to Claim 2, wherein the backing member and the protective member each has a thickness in a range of from 10 to 300 μm .

Claim 7 (New): The wafer dicing/die bonding sheet according to Claim 2, wherein the adhesive layer has a thickness in a range of from 1 to 50 μm .

Claim 8 (New): A method of making a wafer dicing/die bonding sheet, the method comprising

- applying an adhesive composition onto a backing member;
- drying the adhesive composition to form an adhesive layer;
- placing a protective member on the adhesive layer; and
- producing the wafer dicing/die bonding sheet of Claim 2.